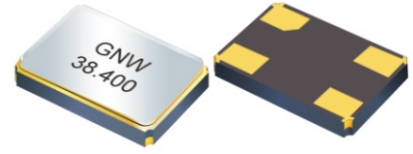


1.6×1.2 SMD Crystal



APPLICATIONS

- Bluetooth / Wireless LAN
- Wearable Devices
- LTE / SAS

FEATURE

- Rugged AT-cut crystal construction
- Miniature 1.6×1.2mm ceramic package
- Anti-EMI design

- Tight Tolerance and Stability
- Reflow Soldering/Emboss Taping



Electrical Specifications 电气参数

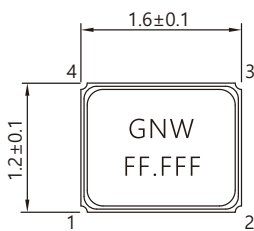
项目	Item/Type	Electrical Specifications
频率范围	Frequency Range	26MHz to 54MHz
调整频差	Frequency Tolerance(at 25°C)	±10ppm to ±30ppm
温度频差	Frequency Drift	±10ppm to ±30ppm
工作温度范围	Operating Temperature Range	-20°C ~ +70°C, -40°C ~ +85°C or -40°C ~ +105°C
储存温度范围	Storage Temperature Range	-55°C ~ +125°C
老化	Aging (25°C)	±3ppm/year max.
静电容	Shunt Capacitance (C0)	3pF max.
激励功率	Drive Level	10µW Typical
绝缘阻抗	Insulation Resistance (Rs)	500 Megaohms min. at D.C 100v
负载电容	Load Capacitance (CL)	6,8,12pF or specify

Equivalent Series Resistance and Mode of Operation 等效阻抗和振荡模式

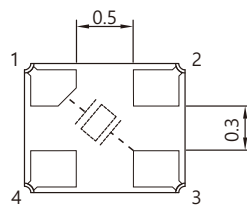
Frequency Range 频率范围	ESR (Ω) 等效阻抗	Mode 振荡模式
26~32MHz	150Ω max.	Fundamental
32~38MHz	100Ω max.	Fundamental
38~54MHz	80Ω max.	Fundamental

Mechanical Dimensions 外型尺寸

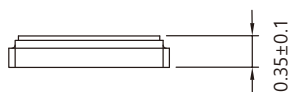
Units:mm



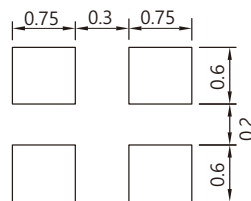
Top View



Bottom View



Side View



Land Pattern

Pin Connection

#1,#3	Crystal
#2,#4	GND